

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	611936	photoresist resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:11
L6	2115	((257/E23.095) or (257/E23.124) or (257/E23.125)).CCLS.	USPAT; USOCR	OR	OFF	2007/08/03 23:02
L7	558	6 and L2 and (@ad < "20031023")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:42
L8	2596576	chip die dice ic integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:58
L9	4942078	encapsula\$8 resin epoxy liquid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:58
L10	3253561	port tube vent\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:58
L11	2748341	temporar\$6 interim provision\$4 short-term transition\$4 sacrificial\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:58
L12	2	(L11 near4 (seal\$4 plug stopper stoppage) with L10 same L9 and L8). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:59
L13	611936	photoresist resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 23:01
L14	222	L8 and (L10 with L13 with L9)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 23:01

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L15	4	(L8 and (L10 with L13 with L9)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 23:02
L16	1542	((438/124) or (438/126)).CCLS.	USPAT; USOCR	OR	OFF	2007/08/03 23:03
S10 9	4	(("6303986") or ("6541314") or ("6566745") or ("6588949")).PN.	USPAT; USOCR	OR	OFF	2007/08/02 17:54
S11 0	187	brewster-william-m.xp.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:00
S11 1	3437253	seal\$4 bond\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:00
S11 2	85	S110 and S111	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:03
S11 3	611936	photoresist resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:11
S11 4	152488	hermetic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:03
S11 5	2596576	chip die dice ic integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:11
S11 6	398	S113 with S114	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:04
S11 7	186	S115 and S116	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:06

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S11 8	2	michael-don.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:06
S12 0	2	rossman-mari-j.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:07
S12 1	2	S118 S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:07
S12 2	145	S117 and (@ad < "20031023")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:09
S12 3	2596576	chip die dice ic integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:12
S12 4	145	S116 and S123 and (@ad < "20031023")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:22
S12 6	611936	photoresist resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:11
S12 7	2596576	chip die dice ic integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:12
S12 8	5271584	port tube vent\$4 hole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:26
S13 0	4942078	encapsula\$8 resin epoxy liquid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 20:57

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S13 1	1243	S127 and (S128 with S126 with S130)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:26
S13 2	904	S131 and (@ad < "20031023")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:27
S13 3	3253561	port tube vent\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 19:26
S13 4	222	S127 and (S133 with S126 with S130)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 20:40
S13 5	177	S134 and (@ad < "20031023")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 23:00
S13 6	2748341	temporar\$6 interim provision\$4 short-term transition\$4 sacrifical\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 20:44
S13 7	59	S136 near4 (seal\$4 plug stopper stoppage) with S133 same S130 and S127	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:58
S13 8	49	S137 and (@ad < "20031023")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 22:11
S13 9	1603828	((encapsula\$8 resin epoxy) or ((fill surround\$4) near4 liquid)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 20:58
S14 0	10535	S126 with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 20:58

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S14 1	102	S139 and S140 and S127 and (@ad < "20031023")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 20:59
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